

# Technical Data Sheet

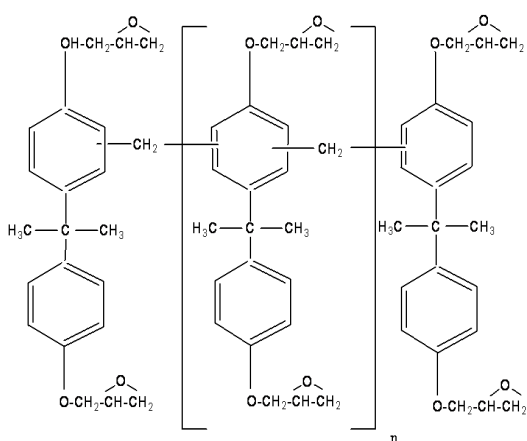
## KEB-3180

### Bisphenol A Novolac Epoxy

#### General Description

The KEB-3180, Bisphenol A novolac based epoxy resin, can give improved high temperature strength, heat stabilities, reaction and chemical resistance because of its multi-functional epoxy groups in a molecule. It also provides higher crosslinked property than general Bisphenol A type epoxy resin. KEB-3180 is a high molecular type of KEB series and can be used for high temperature adhesives, FR-5 type printed circuit board and high Tg for powder coating or laminates.

#### Chemical Structure



#### Resin Properties

Property	Typical values
EEW(g/eq)	190~235
S.P.(°C)*1	80 ± 5
Hy-Cl(ppm)	500 max.
Color(G)	6 max.

\*1 Ball & Ring method

#### Usage

1. High temperature adhesives
2. Electronic encapsulation and transfer molding
3. Electrical heat resistance molding compounds
4. High temperature reinforced plastics applications
5. FR-5 type printed circuit board
6. High Tg for powder coating and laminates

#### Storage

Keep in cool, dry, ventilate condition and in closed containers.

Keep away from heat sources and direct sunlight. Recommended safe handling procedures are discussed in the information on the MSDS should reviewed and understood before working.

#### Packaging

Paper bag of 20 kg net weight

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